

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

1. (Currently Amended) A housing for electronic equipment comprising:
a metal base board including a first main surface and a second main surface, said second main surface being provided at an opposing side of said first main surface, said metal base board having at least one through hole extending from said first main surface to said second main surface, said at least one through hole being configured to facilitate an outsert-molding process;

~~one or more~~ a components ~~that are joined to~~ integrally molded with said metal base board by said outsert-molding process; and

wherein at least one part of a terminal part of said metal base board at ~~said one or more~~ side walls is provided with a convex shape which is not joined to said ~~one or more~~ components, said terminal ~~part~~ part extending in a direction that is substantially perpendicular to the first main surface.

2. (Currently Amended) A housing for electronic equipment comprising:
a metal base board including a first main surface and a second main surface provided at an opposing side of said first main surface, said metal base board having a first terminal part and a second terminal part;

~~one or more~~ a non-metallic components substantially covering said first main surface of said metal base board, said ~~one or more~~ non-metallic components being ~~joined to~~ integrally molded with said metal base board by outsert-molding;

one or more side walls in which said metal base board and said one or more components are joined, wherein said first terminal part is provided at a first edge of said ~~one or more~~ side walls and has a concave shape and said second terminal part is provided at a second

edge of said one or more side walls and has a convex shape, said second terminal part extending in a direction substantially perpendicular to the first main surface.

3. (Currently Amended) A housing for electronic equipment comprising:
a metal base board including a first main surface and a second main surface
provided at an opposing side of said first main surface;

a non-metallic layer ~~joined to~~ integrally molded with first main surface of metal base board by outsert-molding, said non-metallic layer being of thermoplastic polymer material;
and

a plurality of side walls formed by joining a vertical extension of said metal base board and a non-metallic component of thermoplastic polymer material,

wherein at least one corner is formed by first and second side walls of said plurality of side walls, said first and second side walls being separated by a space .

4. (Amended) A housing for electronic equipment comprising:
a metal base board including a first main surface, a second main surface, a plurality of through holes extending from said first and second main surfaces;

first and second side walls, said side walls being provided at edges of said first main surface; and

a ~~plurality of~~ components formed by an outsert-molding process using said plurality of through holes, ~~a first component of said components being joined to integrally molded with~~ said first main surface of said metal base board and substantially covering the first main surface, ~~a second component of said components being joined to said first side wall,~~

wherein said second side wall is not ~~joined to integrally molded with any of~~ said components and a ratio of thickness of said metal base board to a total thickness of said housing is in a range of 1% to 12%, said total thickness including a thicknesses of said first component ~~joined to integrally molded with~~ said first main surface of said metal base board and a thickness of said metal base board.

5. (Previously Presented) The housing of claim 4, wherein said ratio of thickness of said metal base board to said total thickness of said housing is in a range of 8% to 12%.

6. (Currently Amended) A housing for electronic equipment comprising:
a metal base board including a first main surface and a second main surface;
first and second side walls, said side walls being provided at edges of said first main surface; and

~~one or more~~ a components that ~~are joined to~~ is integrally molded with the metal base board by outsert-molding, said components ~~joined to~~ integrally molded with said first main surface and said first side wall and not ~~joined to~~ integrally molded with said second sidewall, said components substantially covering the first main surface,

wherein a ratio of thickness of said metal base board to total thickness of the housing is in a range of 30% to 50%, said total thickness including a thicknesses of ~~the~~ said components ~~joined to~~ integrally molded with said first main surface of said metal base board and a thickness of said metal base board.

7. (Previously Presented) The housing for electronic equipment according to claim 1, wherein a development shape of said metal base board has said at least one through hole, and has a notch of an arbitrary angle at one or more corners of the development shape.

9. (Currently Amended) The housing for electronic equipment according to claim 1, wherein on a surface of said components ~~joined to~~ integrally molded with said metal base board, said component is formed in a concave shape at least one of portions corresponding to said through hole of said metal base board.

10-13. Previously Canceled.

14. (Previously Presented)) The housing of claim 4, wherein said ratio of thickness of said metal base board to total thickness of said housing is in a range of 1% to 5%.

15. (Currently Amended) An electronic device, comprising:

circuitry; and

a housing enclosing said circuitry, said housing including

a metal base board including a first main surface and a second main surface provided at an opposing side of said first main surface, said metal base board having at least one through hole extending from said first main surface to said second main surface, said at least one through hole being configured to facilitate an outsert-molding process,

~~one or more a components that are joined to~~ that is integrally molded with said metal base board by said outsert-molding process, and

wherein at least one part of a terminal part of said metal base board at said one or more side walls is formed in a convex shape which is not joined to said one or more components, said terminal port extending in a direction that is substantially perpendicular to the first main surface.

16. (Previously Presented) The housing of claim 3, wherein said vertical extension including a protruding portion proximate an edge of said first main surface, said protruding portion extending in a direction substantially perpendicular to said first main surface.

17. (Previously Presented)) The housing of claim 16, wherein said protruding portion is configured to facilitate separation of said non-metallic component from said metal base board.